

#### **500V N-Channel MOSFET**

# **General Description**

These N-Channel enhancement mode power field effect transistors are produced using advanced technology which has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies and active power factor correction.

### **Features**

- 100% avalanche tested
- Fast Switching
- Improved dv/dt capability

# **Product Summery**

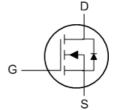
BVDSS	RDSON	ID
500V	0.26 Ω	20A

# **Applications**

- Switching regulators
- UPS (Uninterruptible Power Supply)
- DC-DC converters

# **TO247 Pin Configuration**





### **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units	
V <sub>DS</sub>	Drain-Source Voltage 500			
$V_{GS}$	Gate-Source Voltage	±30	V	
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current 20			
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current 11			
I <sub>DM</sub>	Pulsed Drain Current <sup>1</sup> 60		А	
EAS	Single Pulse Avalanche Energy <sup>2</sup>	860	mJ	
I <sub>AS</sub>	Avalanche Current 20		А	
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation 280		W	
T <sub>STG</sub>	Storage Temperature Range -55 to 150		°C	
$T_J$	Operating Junction Temperature Range -55 to 150		°C	

# **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-ambient		40	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-case		0.44	°C/W



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# Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	500			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃, I <sub>D</sub> =250uA		0.5		V/℃
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =10V , I <sub>D</sub> =10A			0.26	Ω
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	2		4	V
	Danie Course Leelse ee Current	V <sub>DS</sub> =500V, V <sub>GS</sub> =0V			1	
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =400V , V <sub>GS</sub> =0V , TC=125℃			10	uA
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}=\pm30V$ , $V_{DS}$ =0V			±100	nA
gfs	Forward Transconductance 3	V <sub>DS</sub> =40V , I <sub>D</sub> =10A		24		S
Qg	Total Gate Charge	I <sub>D</sub> =20A		52	69	
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =400V		18		nC
Q <sub>gd</sub>	Gate-Drain Charge	V <sub>GS</sub> = 10V (Note 3, 4)		26		
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DS</sub> =250V		88		
Tr	Rise Time	I <sub>D</sub> =20A		270		20
T <sub>d(off)</sub>	Turn-Off Delay Time	R <sub>G</sub> =25Ω		105		ns
T <sub>f</sub>	Fall Time	(Note 3, 4)		117		
C <sub>iss</sub>	Input Capacitance			2500		
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =25V , V <sub>GS</sub> =0V , f=1MHz		380		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			35		

# **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			20	Α
I <sub>SM</sub>	Pulsed Source Current				60	Α
V <sub>SD</sub>	Diode Forward Voltage	V <sub>GS</sub> =0V , I <sub>S</sub> =20 A , T <sub>J</sub> =25℃			1.4	V

#### Note

<sup>1.</sup>Repetitive Rating: Pulse width limited by maximum junction temperature

<sup>2.</sup>L = 4.1mH, IAS = 20A, VDD = 50V, RG = 25Ω, Starting TJ = 25 $^{\circ}$ C

<sup>3.</sup>Pulse Test: Pulse width≤300µs, Duty Cycle≤2%

<sup>4.</sup> Essentially Independent of Operating Temperature Typical Characteristics